Abstract

Leadframe and component with a leadframe

The invention proposes a leadframe of a conductive material, having a central region (14) to accommodate a chip, and a plurality of connecting fingers (12) which extend at least from one side in the direction of the central region (14), a contact region (34) being provided adjacent to the central region (14) on at least some of the connecting fingers (12). The course of the connecting fingers is in this case such that the sectional face in an arbitrary imaginary cross section at right angles to the main face of the leadframe (10) has leadframe material. In this case, it is attempted to keep cross sections in a component without leadframe material as small as possible.

Figure 1

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